<table>
<thead>
<tr>
<th>ALL ARTWORK VIEWED FROM TOP SIDE</th>
<th>BOARD #: PMP10532</th>
<th>REV: B</th>
<th>SUN REV: Not In VersionControl</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = Top Solder</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Top Solder Mask</td>
<td>GENERATED 10/22/2014 12:37:47 AM</td>
<td>TEXAS INSTRUMENTS</td>
<td></td>
</tr>
</tbody>
</table>
## Drill Table

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Hit Count</th>
<th>Tool Size</th>
<th>Plated</th>
<th>Hole Type</th>
</tr>
</thead>
<tbody>
<tr>
<td>-</td>
<td>5</td>
<td>7.874 mil (0.2 mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>○</td>
<td>26</td>
<td>15 mil (0.381 mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>★</td>
<td>9</td>
<td>40 mil (1.016 mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td>×</td>
<td>8</td>
<td>98.425 mil (2.5 mm)</td>
<td>PTH</td>
<td>Round</td>
</tr>
<tr>
<td></td>
<td>48</td>
<td>Total</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**NOTICE:**

- ALL ARTWORK VIEWED FROM TOP SIDE
- BOARD #: PMP10532
- REV: B
- SUN REV: Not In VersionControl
- LAYER NAME = Drill Drawing
- PLOT NAME = Drill Drawing
- GENERATED: 10/22/2014 12:37:50 AM
- TEXAS INSTRUMENTS
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